



S/N 09/733,289

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Xiao-Chun Mu et al.	Examiner:	DiLinh Nguyen
Serial No.:	09/733,289	Group Art Unit:	2814
Filed:	December 8, 2000	Docket No.:	884.798US1
Title:	Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers		
Assignee:	Intel Corporation	Customer No:	21186

RESPONSE UNDER 37 CFR § 1.111

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This responds to the Office Action mailed on April 7, 2005. Please consider the following remarks.